Ultrafast Power Rectifier, Surface Mount

Plastic SOD-123FL Package

NHP120SF, NRVHP120SF

This SOD-123FL ultrafast rectifier provides fast switching performance with soft recovery in a compact thermally efficient package. Its compact footprint makes it ideally suited to portable and automotive applications where board space is at a premium. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

Features

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile Maximum Height of 1.0 mm
- Small Footprint Footprint Area of 5.94 mm²
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 11.7 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

Applications

- Instrumentation
- Output Rectification in Switching Power Supplies Including Mini Adaptors and Flat Panel Display
- LED Lighting
- Freewheeling Diode Where Space is at a Premium



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ULTRAFAST RECTIFIER 1.0 AMPERES 200 VOLTS



SOD-123FL CASE 498

MARKING DIAGRAM



P12 = Specific Device Code

M = Date Code= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NHP120SFT3G	SOD-123 (Pb-Free)	10000 / Tape & Reel
NRVHP120SFT3G	SOD-123 (Pb-Free)	10000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NHP120SF, NRVHP120SF

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (T _L = 158°C)	I _O	1.0	Α
Peak Repetitive Forward Current (Square Wave, 20 kHz, T _L = 155°C)	I _{FRM}	2.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	30	Α
Storage and Operating Junction Temperature Range (Note 1)	T _{stg} , T _J	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	Ψ_{JCL}	23	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	85	°C/W
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{ heta JA}$	330	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 4) $ \begin{array}{l} (I_F=1.0 \text{ A}, T_J=25^{\circ}\text{C}) \\ (I_F=2.0 \text{ A}, T_J=25^{\circ}\text{C}) \\ (I_F=1.0 \text{ A}, T_J=125^{\circ}\text{C}) \\ (I_F=2.0 \text{ A}, T_J=125^{\circ}\text{C}) \end{array} $	V _F	1.0 1.1 0.85 0.95	V
Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$)	I _R	0.5 25	μΑ
Reverse Recovery Time $I_F=1.0$ A, $V_R=30$ V, $dI/dt=50$ A/ μ s, $T_J=25^{\circ}C$	t _{rr}	25	ns
Reverse Recovery Time I _F = 1.0 A, V_R = 30 V, dl/dt = 50 A/ μ s, T_J = 50°C	t _{rr}	50	ns
Maximum Non–Repetitive Avalanche Energy T _J = 25°C	E _{AS}	10	mJ

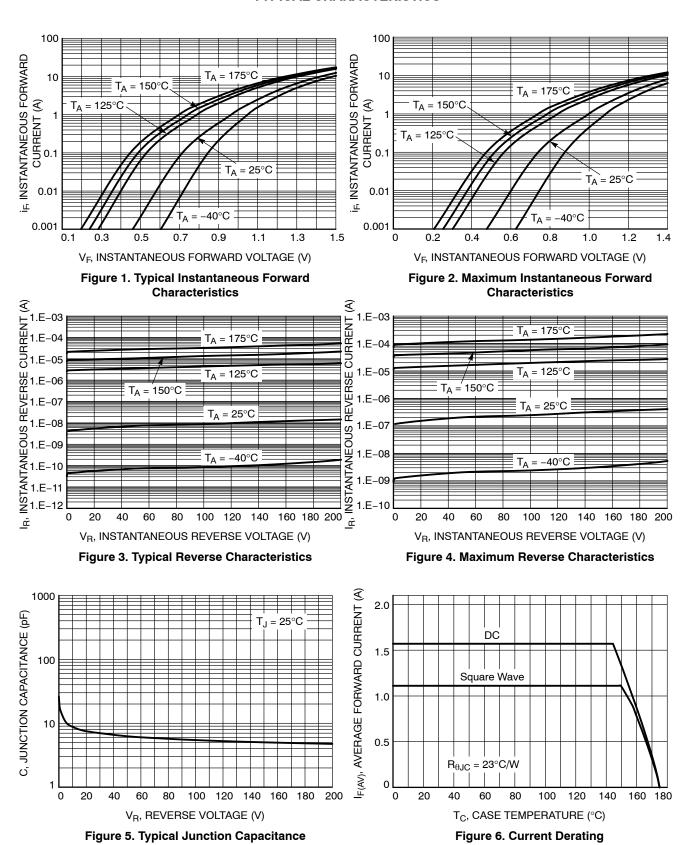
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 2. Mounted with 700 mm² copper pad size (Approximately 1 in²) 1 oz FR4 Board.
- 3. Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board.
- 4. Pulse Test: Pulse Width \leq 380 $\mu s,$ Duty Cycle \leq 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

NHP120SF, NRVHP120SF

TYPICAL CHARACTERISTICS



NHP120SF, NRVHP120SF

TYPICAL CHARACTERISTICS

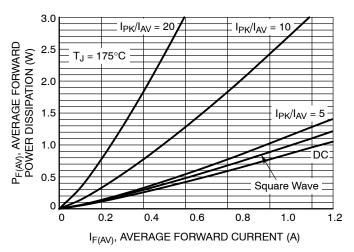


Figure 7. Forward Power Dissipation

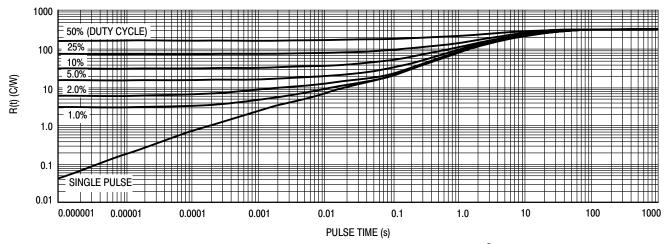


Figure 8. Thermal Response, Junction-to-Ambient (20 mm² pad)

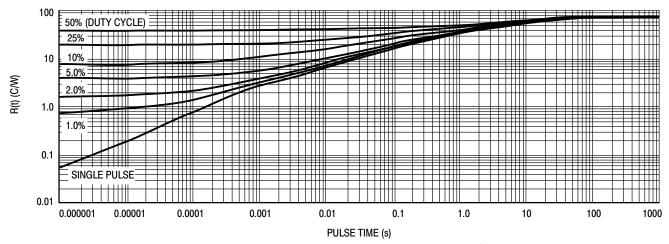
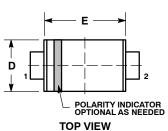


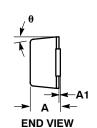
Figure 9. Thermal Response, Junction-to-Ambient (1 in² pad)

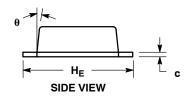


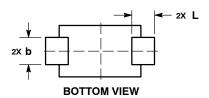
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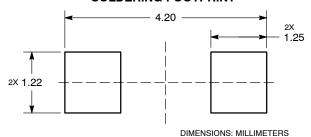








RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- ES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
 DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION
 OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	0.95	0.98	0.035	0.037	0.039
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.70	0.90	1.10	0.028	0.035	0.043
С	0.10	0.15	0.20	0.004	0.006	0.008
D	1.50	1.65	1.80	0.059	0.065	0.071
E	2.50	2.70	2.90	0.098	0.106	0.114
L	0.55	0.75	0.95	0.022	0.030	0.037
HE	3.40	3.60	3.80	0.134	0.142	0.150
θ	0°	-	8°	0°	-	8°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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